



US00D608876S

(12) **United States Design Patent**
Huang et al.

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(45) **Date of Patent:** **** Jan. 26, 2010**

(54) **HEAT DISSIPATION APPARATUS**

D239,118 S * 3/1976 Branson D13/179
6,479,895 B1 * 11/2002 Lee et al. 257/720
D592,613 S * 5/2009 Plonski et al. D13/179

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* cited by examiner

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(**) Term: **14 Years**

(57) **CLAIM**

(21) Appl. No.: **29/338,364**

We claim, the ornamental design for a heat dissipation apparatus, as shown.

(22) Filed: **Jun. 10, 2009**

(30) **Foreign Application Priority Data**

DESCRIPTION

Mar. 21, 2009 (CN) 2009 3 0301586

(51) **LOC (9) Cl.** **23-03**

FIG. 1 is a perspective view of a heat dissipation apparatus showing our new design.

(52) **U.S. Cl.** **D23/323; D13/179**

FIG. 2 is a front elevational view thereof.

(58) **Field of Classification Search** D23/314,
D23/322, 323; D13/179; 165/80.3
See application file for complete search history.

FIG. 3 is a rear elevational view thereof.

FIG. 4 is a left-side, elevational view thereof.

FIG. 5 is a right-side, elevational view thereof.

FIG. 6 is a top plan view thereof; and,

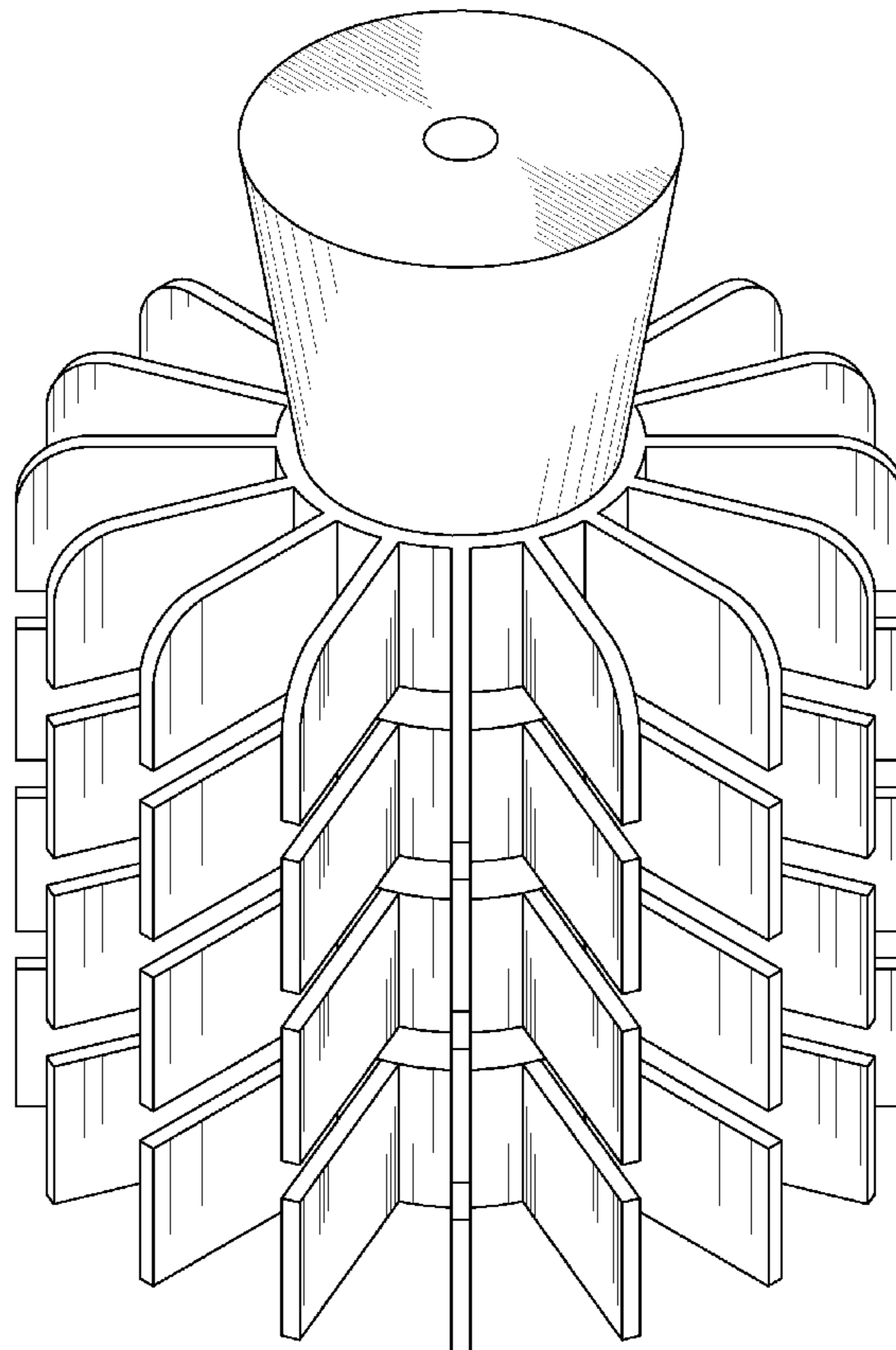
FIG. 7 is a bottom plan view thereof.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D194,787 S * 3/1963 Chadwick D13/179
3,239,003 A * 3/1966 Boudette et al. 165/185

1 Claim, 7 Drawing Sheets



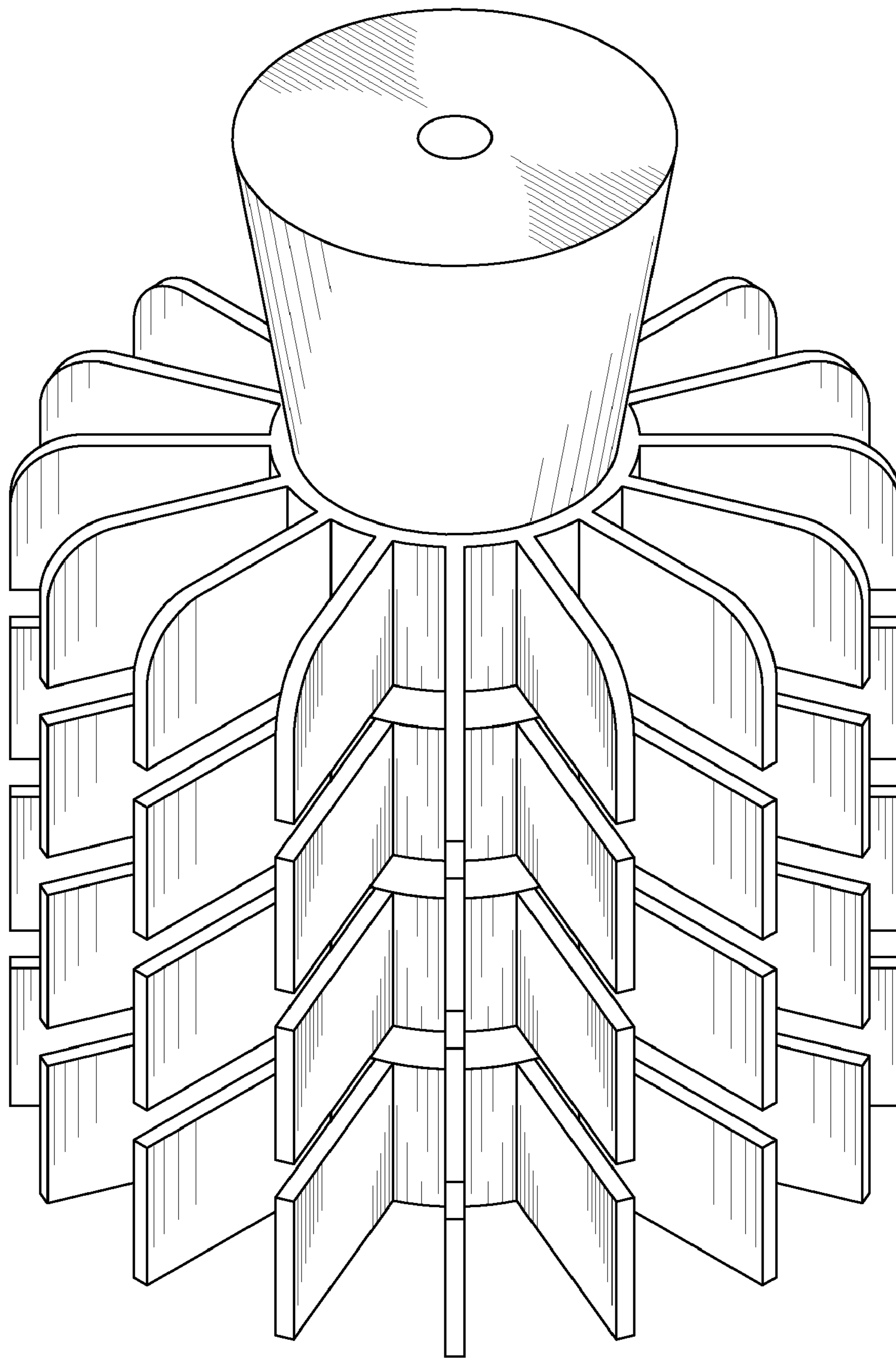


FIG. 1

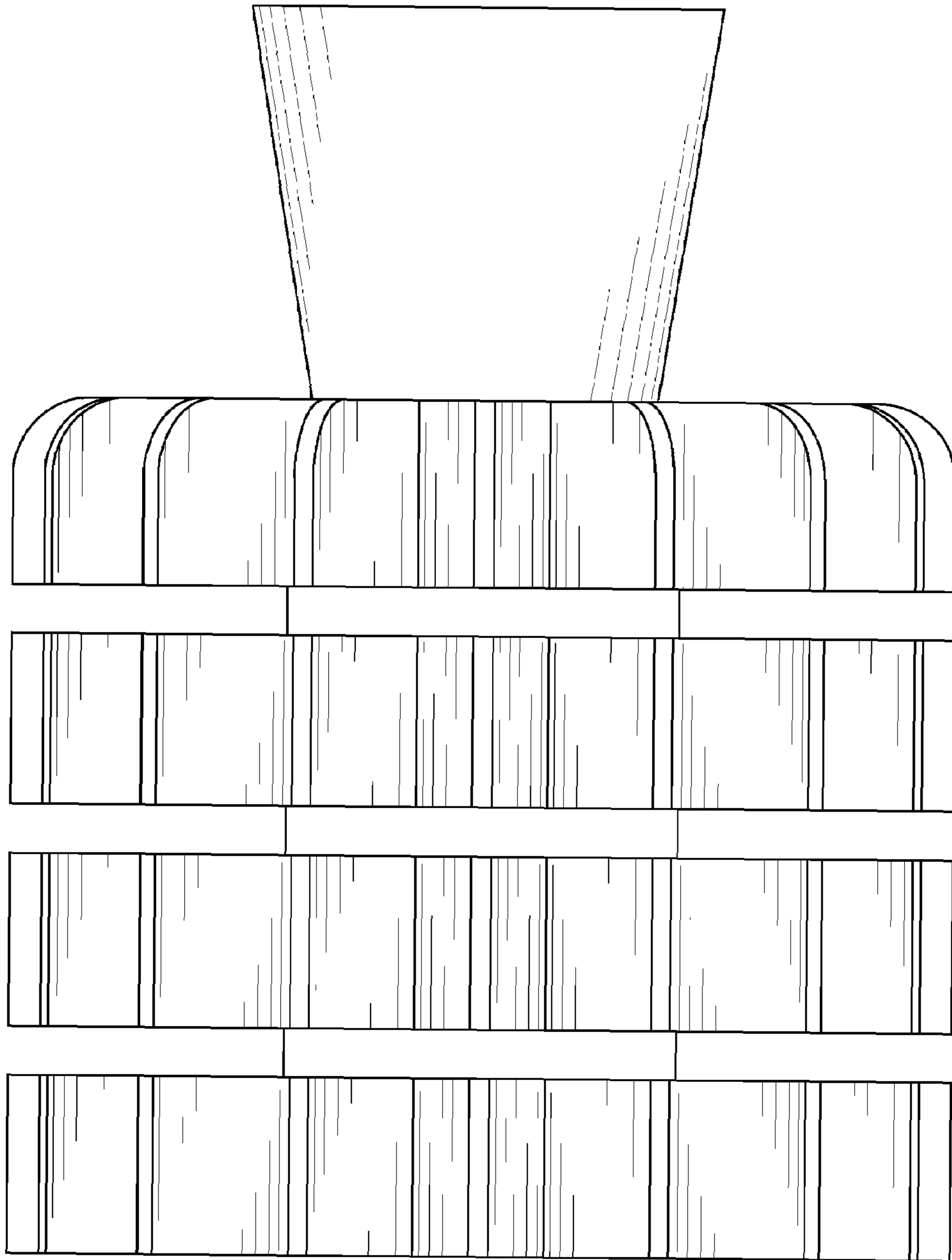


FIG. 2

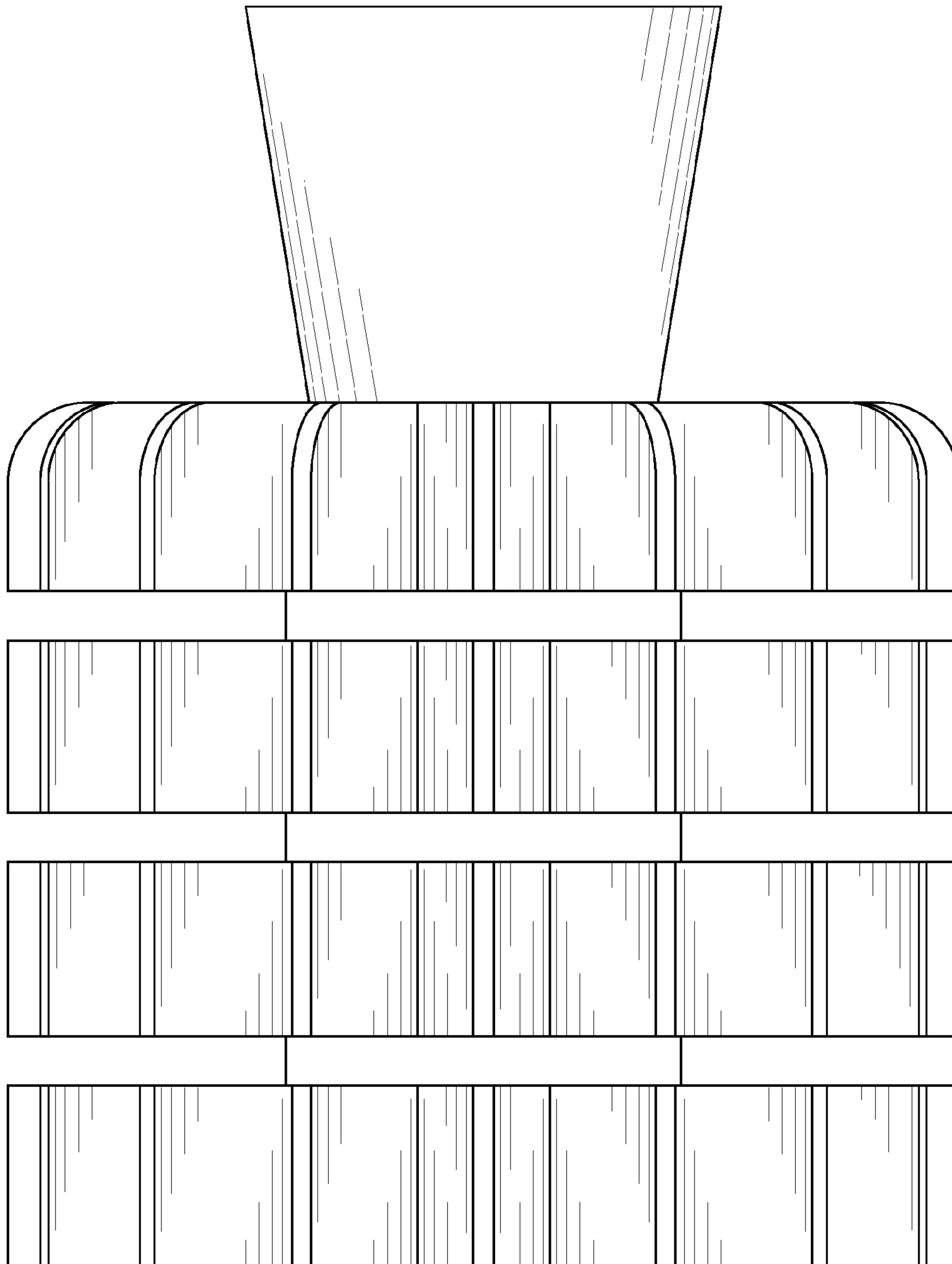


FIG. 3

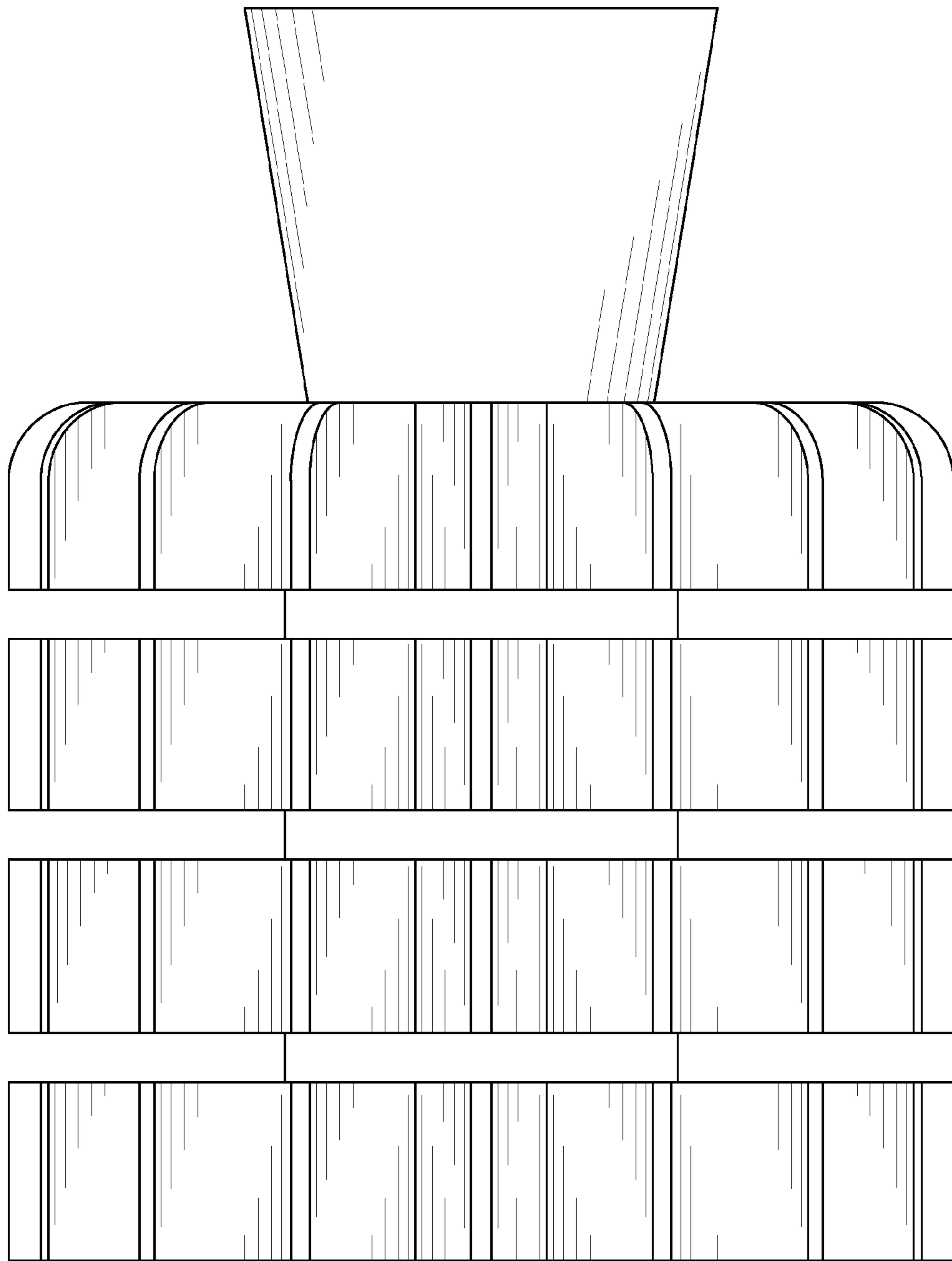


FIG. 4

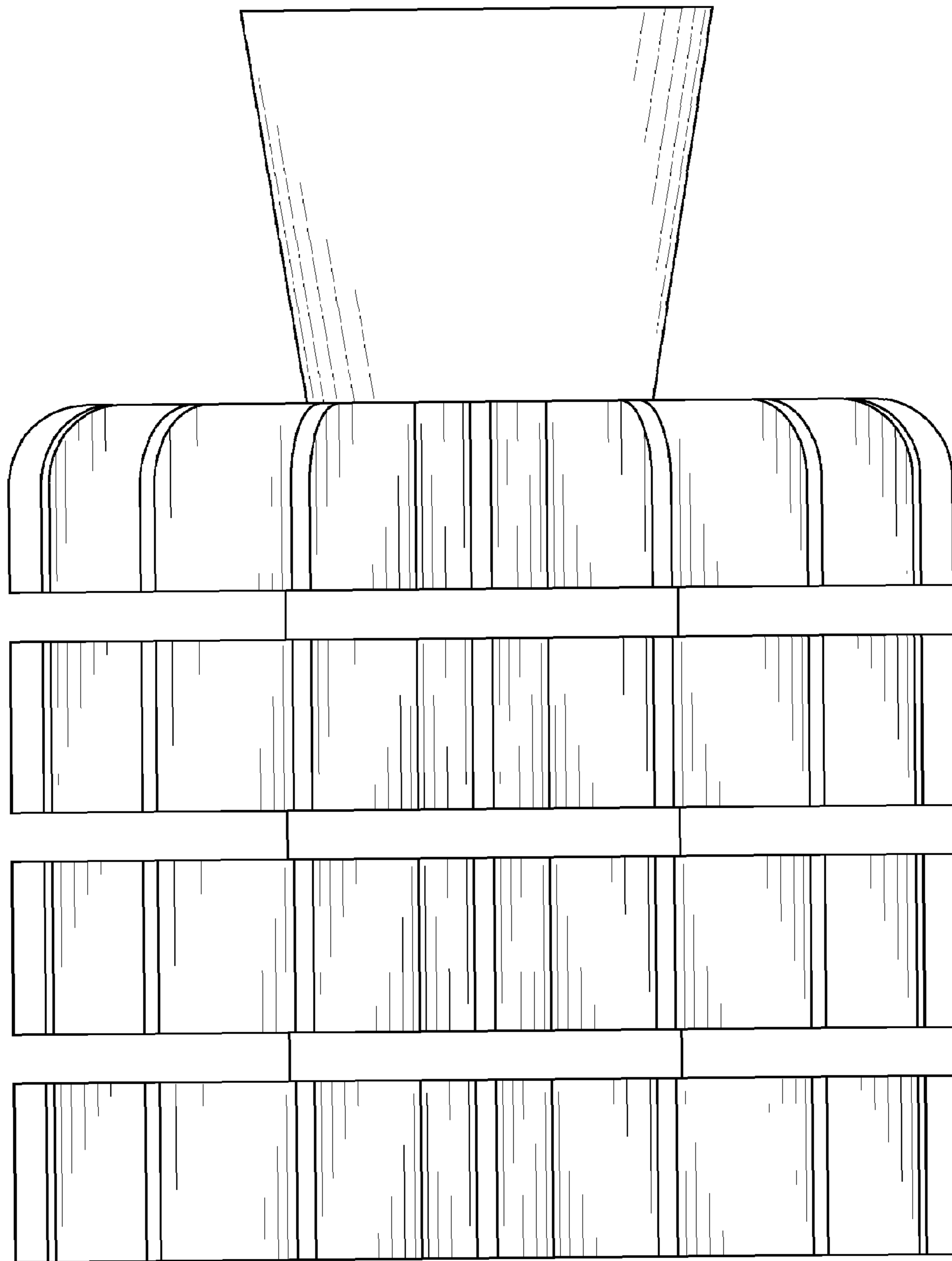


FIG. 5

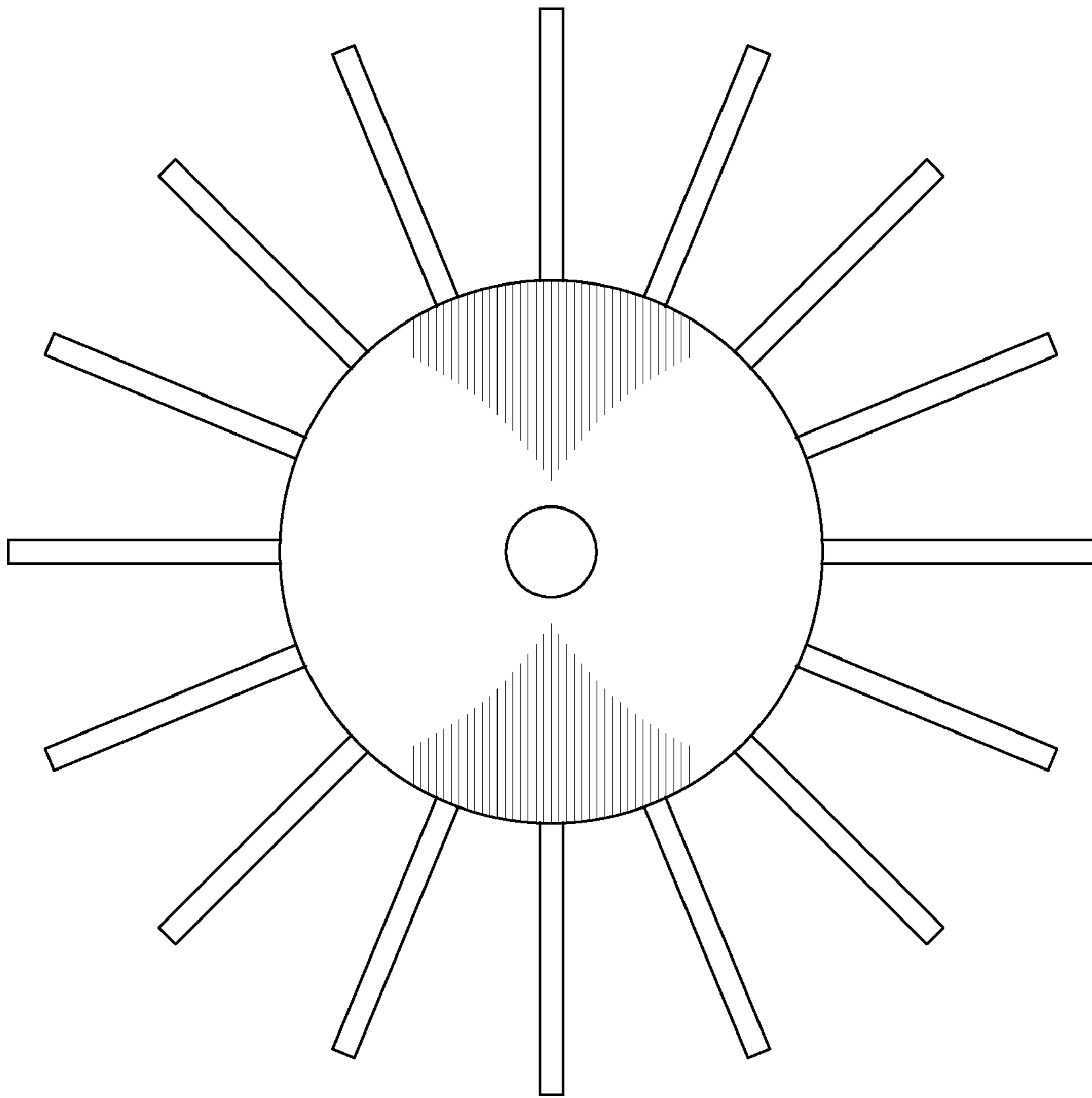


FIG. 6

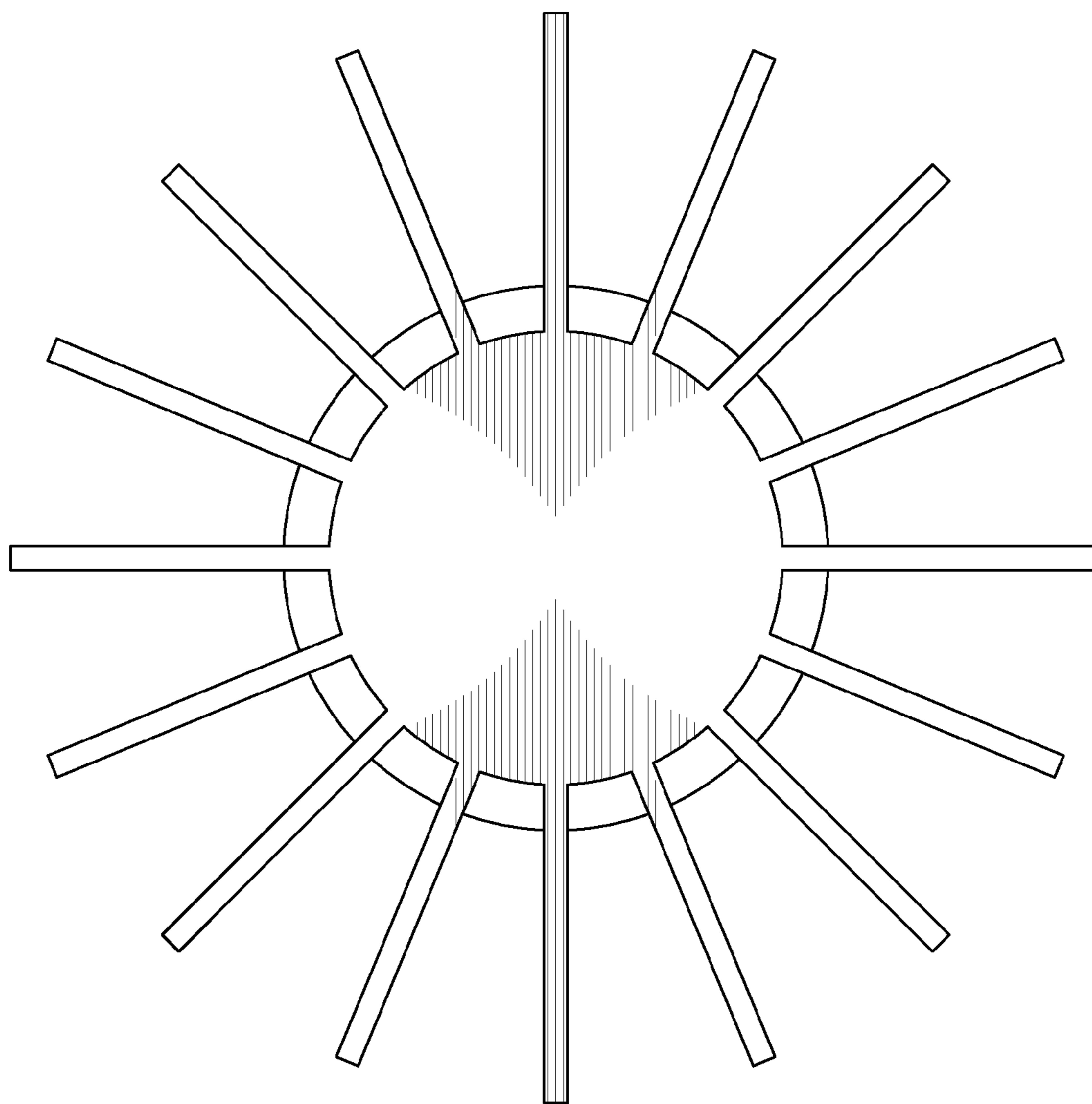


FIG. 7